TPS79301-Q1, TPS79318-Q1, TPS79325-Q1 TPS79328-Q1, TPS793285-Q1, TPS79330-Q1 TPS79333-Q1, TPS793475-Q1

SGLS162E - APRIL 2003 - REVISED JULY 2010

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ULTRALOW-NOISE, HIGH-PSRR, FAST RF 200-mA LOW-DROPOUT LINEAR REGULATORS

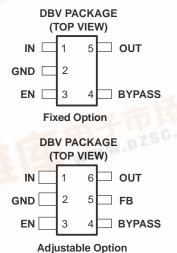
Check for Samples: TPS79301-Q1, TPS79318-Q1, TPS79325-Q1, TPS79328-Q1, TPS793285-Q1, TPS79330-Q1, TPS79333-Q1

FEATURES

- Qualified For Automotive Applications
- 200-mA Low-Dropout Regulator With EN
- Available in 1.8-V, 2.5-V, 2.8-V, 2.85-V, 3-V, 3.3-V, 4.75-V, and Adjustable Options
- High PSRR (70 dB at 10 kHz)
- Ultralow Noise (32 μV)
- Fast Start-Up Time (50 μs)
- Stable With a 2.2-μF Ceramic Capacitor
- Excellent Load/Line Transient
- Very Low Dropout Voltage (112 mV at Full Load, TPS79330)
- 5-Pin SOT23 (DBV) Package

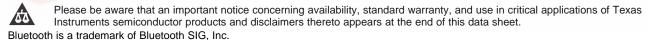
APPLICATIONS

- VCOs
- RF
- Bluetooth™



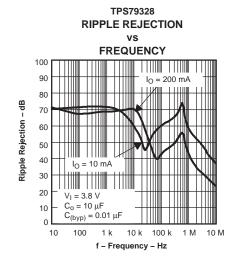
DESCRIPTION

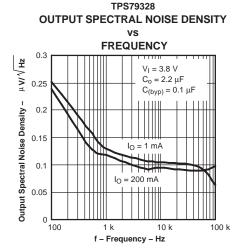
The TPS793xx family of low-dropout (LDO) low-power linear voltage regulators features high power-supply rejection ratio (PSRR), ultralow noise, fast start-up, and excellent line and load transient responses in a small-outline SOT23 package. Each device in the family is stable, with a small 2.2- μ F ceramic capacitor on the output. The TPS793xx family uses an advanced, proprietary, BiCMOS fabrication process to yield extremely low dropout voltages (e.g., 112 mV at 200 mA, TPS79330). Each device achieves fast start-up times (approximately 50 μ s with a 0.001- μ F bypass capacitor), while consuming very low quiescent current (170 μ A typical). Moreover, when the device is placed in standby mode, the supply current is reduced to less than 1 μ A. The TPS79328 exhibits approximately 32 μ V_{RMS} of output voltage noise with a 0.1- μ F bypass capacitor. Applications with analog components that are noise sensitive, such as portable RF electronics, benefit from the high PSRR and low-noise features, as well as the fast response time.



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ORDERING INFORMATION(1)

TJ	OUTPUT VOLTAGE	PACK	AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	1.2 to 5.5 V			TPS79301DBVRQ1	PGV1
	1.8 V		Reel of 3000	TPS79318DBVRQ1	PHH1
	2.5 V			TPS79325DBVRQ1	PGW1
40°C to 425°C	2.8 V	SOT23 – DBV		TPS79328DBVRQ1	PGX1
–40°C to 125°C	2.85 V	30123 - DBV		TPS793285QDBVRQ1	PHI1
	3 V			TPS79330QDBVRQ1	PGY1
	3.3 V			TPS793333QDBVRQ1	PHU1
	4.75 V			TPS793475QDBVRQ1 (3)	PHJ1

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

⁽²⁾ Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

⁽³⁾ Product preview



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SGLS162E - APRIL 2003-REVISED JULY 2010

ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
	Input voltage range ⁽²⁾		-0.3	6	V
	Voltage range at EN		-0.3	V _I + 0.3	V
	Voltage on OUT		-0.3	6	V
	Peak output current				
	CCD ratios	Human-Body Model (HBM)		2000	V
	ESD rating	Changed-Device Model (CDM)			
	Continuous total power dissipation			Dissipa	
TJ	Operating virtual junction temperature range		-40	150	°C
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATINGS

BOARD	PACKAGE	$R_{ heta JC}$	$R_{ hetaJA}$	DERATING FACTOR ABOVE T _A = 25°C	T _A ≤ 25°C POWER RATING	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
Low K ⁽¹⁾	DBV	63.75°C/W	256°C/W	3.906 mW/°C	391 mW	215 mW	156 mW
High K ⁽²⁾	DBV	63.75°C/W	178.3°C/W	5.609 mW/°C	561 mW	308 mW	224 mW

⁽¹⁾ The JEDEC low K (1s) board design used to derive this data was a 3-in x 3-in, two layer board with 2-oz copper traces on top of the board.

⁽²⁾ All voltage values are with respect to network ground terminal

⁽²⁾ The JEDEC high K (2s2p) board design used to derive this data was a 3-in x 3-in, multilayer board with 1-oz internal power and ground planes and 2-oz copper traces on top and bottom of the board.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range, EN = V_I , $T_J = -40$ to 125°C, $V_I = V_{O(typ)} + 1$ V, $I_O = 1$ mA, $C_o = 10$ μ F, $C_{(byp)} = 0.01$ μ F (unless otherwise noted)

	RAMETER	TEST CON	DITIONS	MIN	TYP	MAX	UNIT				
V _I Input voltage	(1)			2.7		5.5	V				
I _O Continuous o	output current ⁽²⁾			0		200	mA				
T _J Operating jur	nction temperature			-40		125	°C				
	TPS79301	$0 \mu A < I_O < 200 \text{ mA},$	$1.22 \text{ V} \le \text{V}_{\text{O}} \le 5.2 \text{ V}$ (3)	0.98 V _O		1.02 V _O					
	TDC70249	$T_J = 25^{\circ}C$			1.8						
	TPS79318	$0 \mu A < I_O < 200 mA$,	2.8 V < V _I < 5.5 V	1.764		1.836					
	TD070005	$T_J = 25^{\circ}C$			2.5						
	TPS79325	$0 \mu A < I_O < 200 mA$,	3.5 V < V _I < 5.5 V	2.45		2.55					
	TD070000	T _J = 25°C			2.8						
	TPS79328	$0 \mu A < I_O < 200 mA$,	3.8 V < V _I < 5.5 V	2.744		2.856					
Output voltage	TD070005	$T_J = 25^{\circ}C$			2.85		V				
	TPS793285	$0 \mu A < I_O < 200 mA$,	3.85 V < V _I < 5.5 V	2.793		2.907					
	TD070000	$T_J = 25^{\circ}C$			3						
	TPS79330	$0 \mu A < I_O < 200 mA$,	4 V < V _I < 5.5 V	2.94		3.06					
	TD070000	T _J = 25°C			3.3						
	TPS79333	$0 \mu A < I_O < 200 mA$,	4.3 V < V _I < 5.5 V	3.234		3.366					
	TD0700475	$T_J = 25^{\circ}C$			4.75						
	TPS793475	$0 \mu A < I_O < 200 mA$,	5.25 V < V _I < 5.5 V	4.655		4.845					
O:	ONID accompant)	$0 \mu A < I_O < 200 mA$,		170	۸						
Quiescent current (C	SND current)	0 μA < I _O < 200 mA		220		μА					
Load regulation		$0 \mu A < I_O < 200 mA$,	T _J = 25°C		5		mV				
0		$V_0 + 1 \text{ V} < V_1 \le 5.5 \text{ V}, \qquad T_J = 25^{\circ}\text{C}$			0.05		0/ 0/				
Output voltage line r	regulation (ΔV _O /V _O) ⁽⁴⁾	V _O + 1 V < V _I ≤ 5.5 V			0.12	%/V					
			$C_{(byp)} = 0.001 \mu F$		55						
Otmt	· /TDC70200\	BW = 200 Hz to 100 kHz,	$C_{(byp)} = 0.0047 \ \mu F$		36						
Output noise voltage	e (1PS/9328)	$I_{O} = 200 \text{ mA}, T_{J} = 25^{\circ}\text{C}$	$C_{(byp)} = 0.01 \mu F$				μV_{RMS}				
			$C_{(byp)} = 0.1 \mu F$		32						
			$C_{(byp)} = 0.001 \mu F$		50						
Time, start-up (TPS	79328)	$R_L = 14 \Omega,$ $C_0 = 1 \mu F, T_J = 25^{\circ}C$	$C_{(byp)} = 0.0047 \mu F$		70		μS				
		$O_0 = 1 \mu i$, $ij = 25 O$	$C_{(byp)} = 0.01 \mu F$		100						
Output current limit		$V_{O} = 0 \ V^{(3)}$		285		600	mA				
Standby current		EN = 0 V,	2.7 V < V _I < 5.5 V		0.07	1	μΑ				
High-level enable in	put voltage	2.7 V < V _I < 5.5 V					V				
Low-level enable inp	out voltage	2.7 V < V _I < 5.5 V				0.7	V				
Input current (EN)		EN = 0	-1		1	μΑ					
Input current (FB) (T	PS79301)	FB = 1.8 V			1	μА					

⁽¹⁾ To calculate the minimum input voltage for your maximum output current, use the following formula: $V_1(min) = V_O(max) + V_{DO}(max load)$

(4) If $V_0 \le 2.5 \text{ V}$, then $V_{\text{Imin}} = 2.7 \text{ V}$, $V_{\text{Imax}} = 5.5 \text{ V}$:

Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{\text{Imax}} - 2.7 \text{ V})}{100} \times 1000$$

If $V_O \ge 2.5 \text{ V}$, then $V_{Imin} = V_O + 1 \text{ V}$, $V_{Imax} = 5.5 \text{ V}$.

⁽²⁾ Continuous output current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.

⁽³⁾ The minimum IN operating voltage is 2.7 V or V_{O(typ)} + 1 V, whichever is greater. The maximum IN voltage is 5.5 V. The maximum output current is 200 mA.



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ELECTRICAL CHARACTERISTICS (continued)

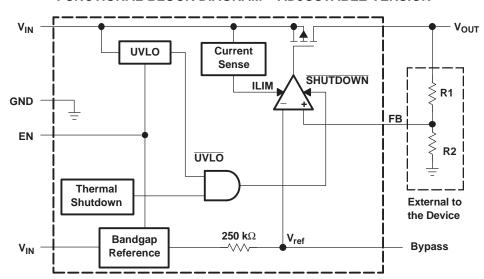
over recommended operating free-air temperature range, EN = V_I , $T_J = -40$ to 125°C, $V_I = V_{O(typ)} + 1$ V, $I_O = 1$ mA, $C_o = 10$ μF , $C_{(byp)} = 0.01$ μF (unless otherwise noted)

PARAM	METER	TEST CO	NDITIONS	MIN TYP	MAX	UNIT	
		f = 100 Hz, T _J = 25°C,	I _O = 10 mA	70			
Power-supply ripple	TD070000	f = 100 Hz, T _J = 25°C,	I _O = 200 mA	68		4D	
rejection	TPS79328	f = 10 Hz, T _J = 25°C,	I _O = 200 mA	70		dB	
		f = 100 Hz, T _J = 25°C,	I _O = 200 mA	43			
	TD070220	$I_{O} = 200 \text{ mA},$	$T_J = 25^{\circ}C$	120			
	TPS79328	I _O = 200 mA			200	200	
	TPS793285	I _O = 200 mA,	T _J = 25°C	120			
		I _O = 200 mA			200		
Dropout voltage ⁽⁵⁾		I _O = 200 mA,	T _J = 25°C	112		m) /	
Dropout voltage (9)	TPS79330	I _O = 200 mA			200	mV	
	TD070000	I _O = 200 mA,	T _J = 25°C	102			
	TPS79333	I _O = 200 mA			180		
	TD0700475	I _O = 200 mA,	T _J = 25°C	77			
	TPS793475	I _O = 200 mA			125		
UVLO threshold		V _{CC} rising		2.25	2.65	V	
UVLO hysteresis		T _J = 25°C	V _{CC} rising	100		mV	

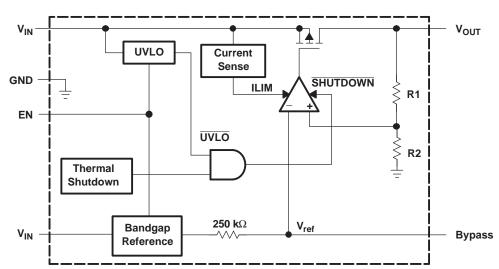
⁽⁵⁾ IN voltage equals $V_{O(tvp)}$ – 100 mV; The TPS79325 dropout voltage is limited by the input voltage range limitations.



FUNCTIONAL BLOCK DIAGRAM – ADJUSTABLE VERSION



FUNCTIONAL BLOCK DIAGRAM - FIXED VERSION

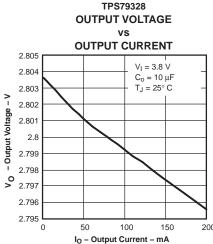


TERMINAL FUNCTIONS

				TERMINAL FORCTIONS
-	TERMINAL		1/0	DESCRIPTION
NAME	ADJ	FIXED	1/0	DESCRIPTION
BYPASS	4	4		An external bypass capacitor, connected to this terminal, in conjunction with an internal resistor, creates a low-pass filter to further reduce regulator noise.
EN	3	3	1	Enable input that enables or shuts down the device. When EN goes to a logic high, the device is enabled. When the device goes to a logic low, the device is in shutdown mode.
FB	5	N/A	ı	Feedback input voltage for the adjustable device
GND	2	2		Regulator ground
IN	1	1	I	Input to the device
OUT	6	5	0	Regulated output of the device



TYPICAL CHARACTERISTICS



2.78 V₁ = 3.8 V C₀ = 10 μF 100 150 200 2.775 -40 -25 -10 5 2

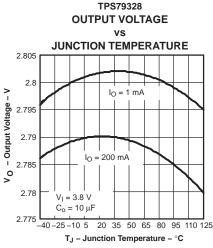


Figure 2.

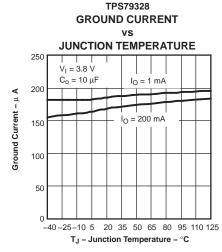


Figure 3.

TPS79328 OUTPUT SPECTRAL NOISE DENSITY

Figure 1.

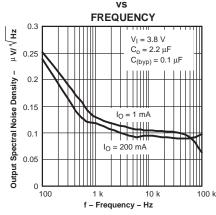


Figure 4.

TPS79328 OUTPUT SPECTRAL NOISE DENSITY vs

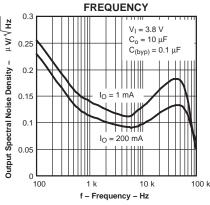


Figure 5.

TPS79328 OUTPUT SPECTRAL NOISE DENSITY vs

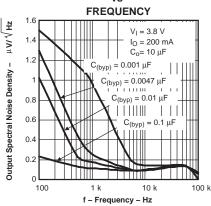


Figure 6.

ROOT MEAN SQUARED OUTPUT NOISE

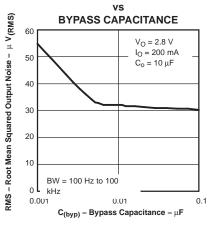


Figure 7.

OUTPUT IMPEDANCE vs FREQUENCY

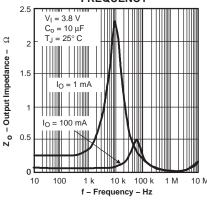


Figure 8.

TPS79328 DROPOUT VOLTAGE

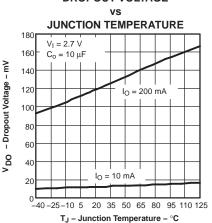
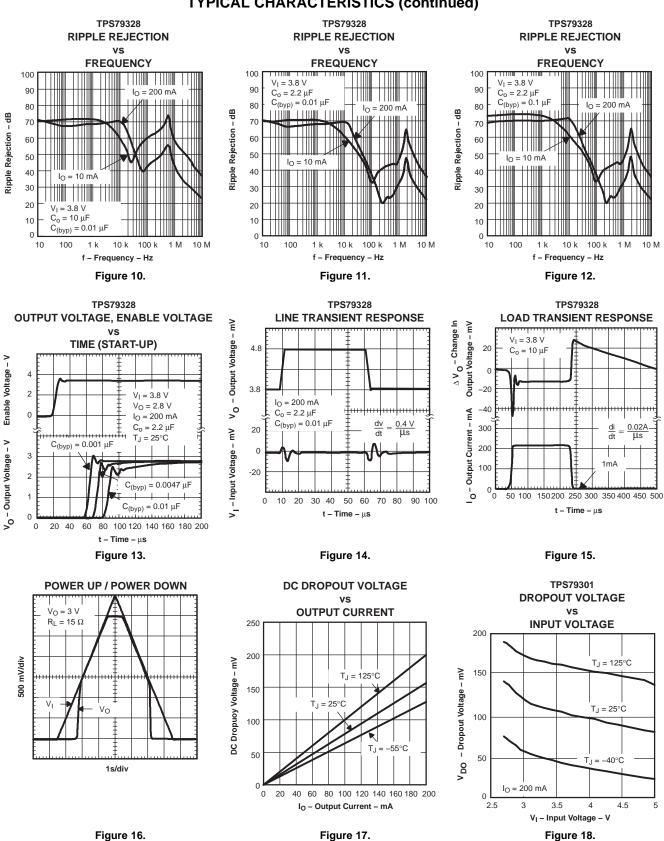


Figure 9.



TYPICAL CHARACTERISTICS (continued)

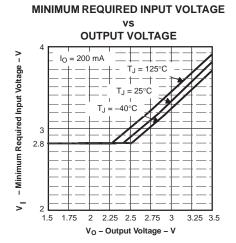




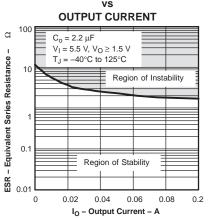
Instruments

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TYPICAL CHARACTERISTICS (continued)



TYPICAL REGIONS OF STABILITY **EQUIVALENT SERIES RESISTANCE (ESR)**



EQUIVALENT SERIES RESISTANCE (ESR) OUTPUT CURRENT

TYPICAL REGIONS OF STABILITY

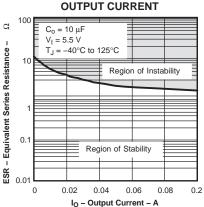


Figure 20.

Figure 21.



APPLICATION INFORMATION

The TPS793xx family of low-dropout (LDO) regulators has been optimized for use in noise-sensitive battery-operated equipment. The device features extremely low dropout voltages, high PSRR, ultralow output noise, low quiescent current (170 μ A typically), and enable-input to reduce supply currents to less than 1 μ A when the regulator is turned off.

A typical application circuit is shown in Figure 22.

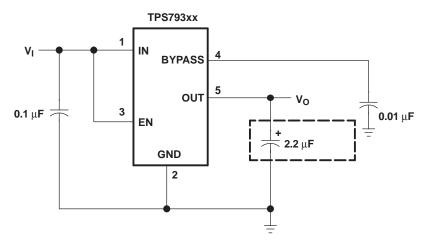


Figure 22. Typical Application Circuit

External Capacitor Requirements

A 0.1- μF or larger ceramic input bypass capacitor, connected between IN and GND and located close to the TPS793xx, is required for stability and improves transient response, noise rejection, and ripple rejection. A higher-value electrolytic input capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source.

Like all LDOs, the TPS793xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance is 2.2-μF. Any 2.2-μF or larger ceramic capacitor is suitable, provided the capacitance does not vary significantly over temperature.

The internal voltage reference is a key source of noise in an LDO regulator. The TPS793xx has a BYPASS pin that is connected to the voltage reference through a 250-k Ω internal resistor. The 250-k Ω internal resistor, in conjunction with an external bypass capacitor connected to the BYPASS pin, creates a low pass filter to reduce the voltage reference noise and, therefore, the noise at the regulator output. In order for the regulator to operate properly, the current flow out of the BYPASS pin must be at a minimum, because any leakage current creates an IR drop across the internal resistor, thus, creating an output error. Therefore, the bypass capacitor must have minimal leakage current.

For example, the TPS79328 exhibits only 32 μV_{RMS} of output voltage noise using a 0.1- μF ceramic bypass capacitor and a 2.2- μF ceramic output capacitor. Note that the output starts up slower as the bypass capacitance increases due to the RC time constant at the BYPASS pin that is created by the internal 250- $k\Omega$ resistor and external capacitor.

Board Layout Recommendation to Improve PSRR and Noise Performance

To improve ac measurements like PSRR, output noise, and transient response, it is recommended that the board be designed with separate ground planes for V_{IN} and V_{OUT} , with each ground plane connected only at the GND pin of the device. In addition, the ground connection for the bypass capacitor should connect directly to the GND pin of the device.

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SGLS162E - APRIL 2003 - REVISED JULY 2010

Power Dissipation and Junction Temperature

Specified regulator operation is ensured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_D , which must be less than or equal to $P_{D(max)}$.

The maximum power dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{J}^{max} - T_{A}}{R_{\theta JA}}$$
(1)

Where:

T₁max = Maximum allowable junction temperature

 $R\theta_{JA}$ = Thermal resistance, junction to ambient, for the package, see the dissipation rating table

 T_A = Ambient temperature

The regulator dissipation is calculated using:

$$P_{D} = (V_{I} - V_{O}) \times I_{O}$$
(2)

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation triggers the thermal protection circuit.

Programming the TPS79301 Adjustable LDO Regulator

The output voltage of the TPS79301 adjustable regulator is programmed using an external resistor divider as shown in Figure 23. The output voltage is calculated using:

$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right) \tag{3}$$

Where:

 V_{ref} = 1.2246 V typical (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 50- μ A divider current. Lower-value resistors can be used for improved noise performance, but the solution consumes more power. Higher resistor values should be avoided as leakage current into/out of FB across R1/R2 creates an offset voltage that artificially increases/decreases the feedback voltage and, thus, erroneously decreases/increases V_O . The recommended design procedure is to choose R2 = 30.1 k Ω to set the divider current at 50 μ A, C1 = 15 pF for stability, and then calculate R1 using:

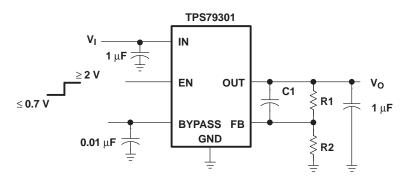
$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2 \tag{4}$$

In order to improve the stability of the adjustable version, it is suggested that a small compensation capacitor be placed between OUT and FB. For voltages <1.8 V, the value of this capacitor should be 100 pF. For voltages >1.8 V, the approximate value of this capacitor can be calculated as:

C1 =
$$\frac{(3 \times 10^{-7}) \times (R1 + R2)}{(R1 \times R2)}$$
 (5)

The suggested value of this capacitor for several resistor ratios is shown in the table below. If this capacitor is not used (such as in a unity-gain configuration) or if an output voltage <1.8 V is chosen, then the minimum recommended output capacitor is 4.7 μ F instead of 2.2 μ F.





OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	C1
2.5 V	31.6 kΩ	30.1 kΩ	22 pF
3.3 V	51 kΩ	30.1 kΩ	15 pF
3.6 V	59 kΩ	30.1 kΩ	15 pF

Figure 23. TPS79301 Adjustable LDO Regulator Programming

Regulator Protection

The TPS793xx features internal current limiting and thermal protection. During normal operation, the TPS793xx limits output current to approximately 400 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package or the absolute maximum voltage ratings of the device. If the temperature of the device exceeds approximately 165°C, thermal-protection circuitry shuts it down. Once the device has cooled down to below approximately 140°C, regulator operation resumes.



PACKA

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pe
TPS79301DBVRG4Q1	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79301DBVRQ1	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79318DBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79318DBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79325DBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79325DBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS793285QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79328QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79330QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79333DBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS79333DBVRQ1	ACTIVE	SOT-23	DBV	5	3000	TBD	CU NIPDAU	Level-1-220
TPS793475DBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS793475DBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260

(1) The marketing status values are defined as follows: ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www. information and additional product content details.



PACKA

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retard in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Cu

 $OTHER\ QUALIFIED\ VERSIONS\ OF\ TPS79301-Q1,\ TPS79318-Q1,\ TPS79325-Q1,\ TPS79328-Q1,\ TPS79328-Q1,\ TPS79330-Q1,\ TPS79333-Q1,\ TPS79330-Q1,\ TPS7930-Q1,\ TPS79300-Q1,\ TPS79300-Q1,\ TPS79300-Q1,\ TPS79300-Q1,\ TPS79300-Q1,\ TPS79300-Q1$

- ◆ Catalog: TPS79301, TPS79318, TPS79325, TPS79328, TPS793285, TPS79330, TPS79333, TPS793475
- Enhanced Product: TPS79301-EP, TPS79318-EP, TPS79325-EP, TPS79333-EP, TPS793475-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

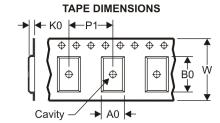


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27-Aug-2010

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

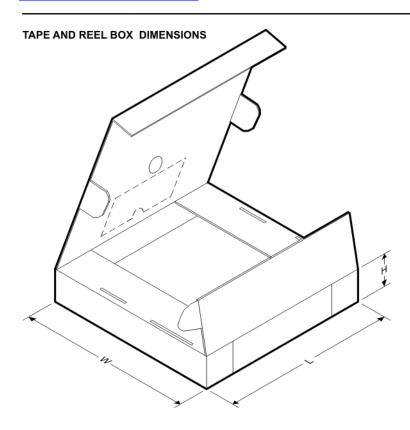
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS79328QDBVRQ1	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS79330QDBVRQ1	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3





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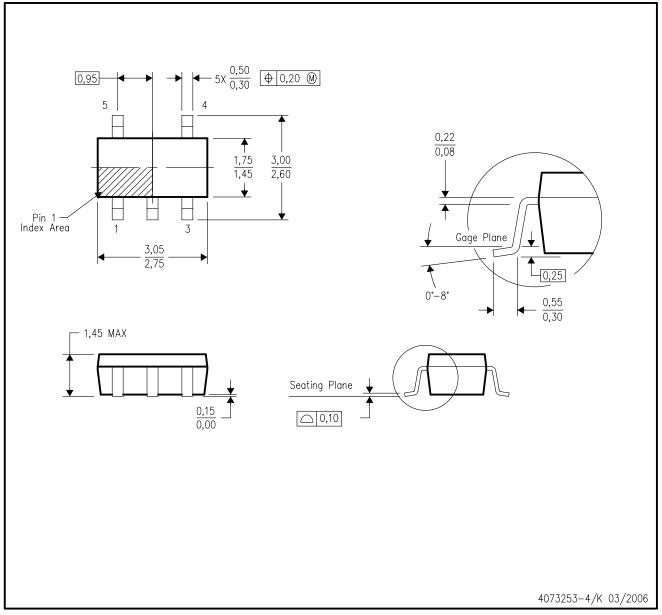


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS79328QDBVRQ1	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS79330QDBVRQ1	SOT-23	DBV	5	3000	203.0	203.0	35.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE

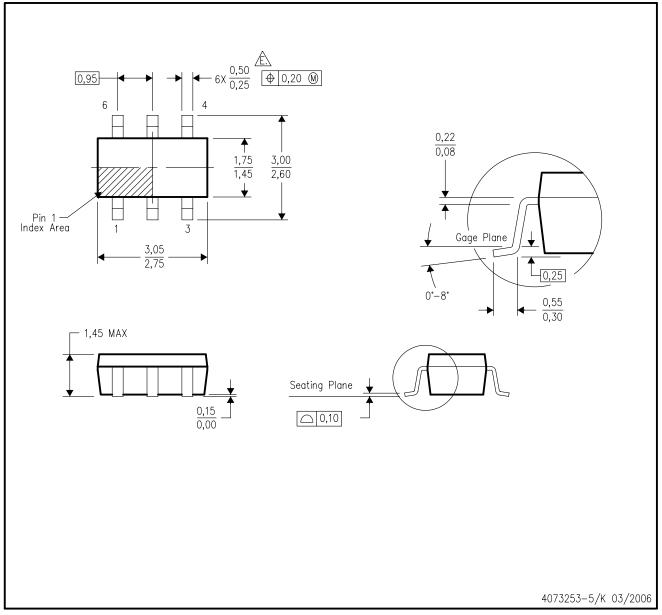


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G6)

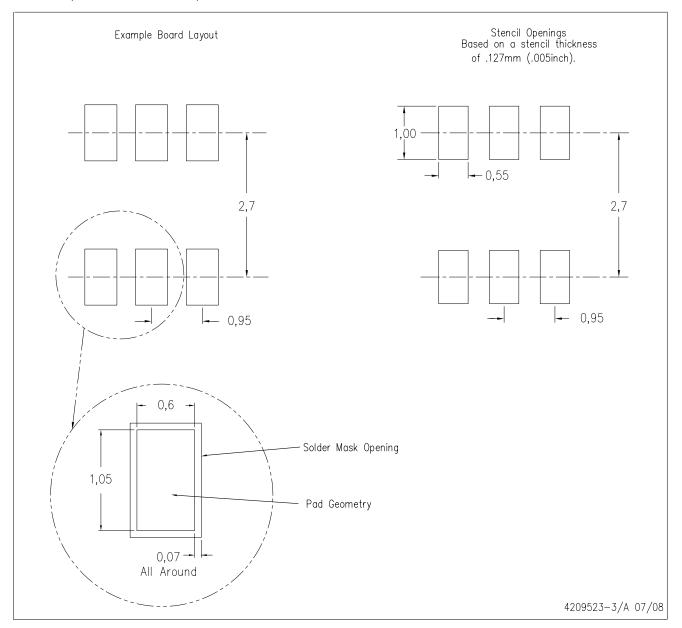
PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



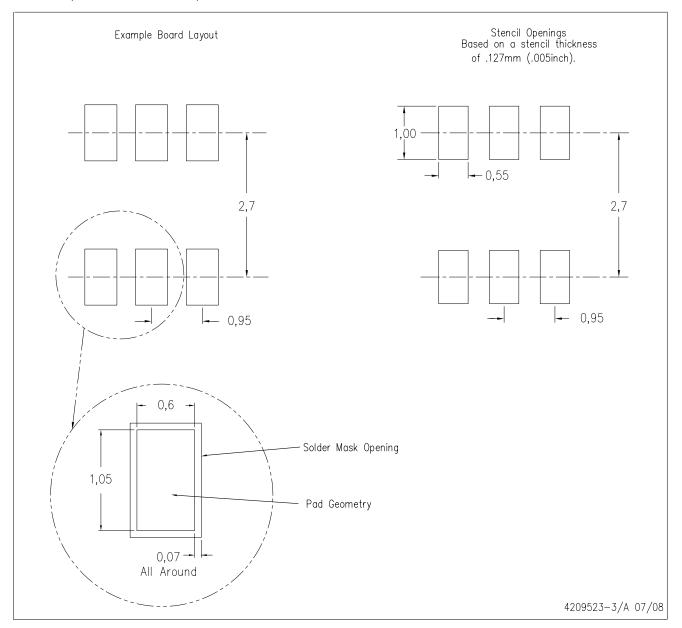
DBV (R-PDSO-G6)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



DBV (R-PDSO-G6)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
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